

10/090287

03/01/02

1115

PATENT NUMBER and  
ISSUE DATE

U.S. UTILITY Patent Application

APPL NUM 10090287	FILING DATE 03/01/2002	CLASS 374	SUBCLASS 005	GAU 2859	EXAMINER 168217548
<b>**APPLICANTS:</b> Borden Peter; Li Ji-Ping;					
<b>**CONTINUING DATA VERIFIED:</b> <i>ho ac</i>					
<b>** FOREIGN APPLICATIONS VERIFIED:</b> <i>ho ac</i>					
PG-FUE		DO NOT PUBLISH <input type="checkbox"/>		RESCIND <input type="checkbox"/>	
Foreign priority claimed		<input type="checkbox"/> yes <input checked="" type="checkbox"/> no		ATTORNEY DOCKET NO	
35 USC 119 conditions met		<input type="checkbox"/> yes <input checked="" type="checkbox"/> no		M-12169 US	
Verified and Acknowledged Examiners's initials					
<b>TITLE :</b> Identifying defects in a conductive structure of a wafer, based on heat transfer therethrough					

<b>NOTICE OF ALLOWANCE MAILED</b>		<b>CLAIMS ALLOWED</b>	
		Total Claims	Print Claim for O.G.
<b>ISSUE FEE</b>		<b>DRAWING</b>	
Amount Due	Date Paid	Sheets Drawg.	Figs Drawg. Print Fig.
<input type="checkbox"/> <b>TERMINAL DISCLAIMER</b>		<b>Assistant Examiner</b>  <b>Primary Examiner</b>  <b>Application Examiner</b>	
		<b>PREPARED F R ISSUE</b>	
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